

Amendments to the Claims:

Please cancel Claims 1-18.

The listing of Claims below replaces all prior versions, and listings, of Claims in the Application.

Listing of Claims:

19 (new). A method of making a circuitized substrate, said method comprising:

providing a dielectric polymer layer;

immersing said dielectric polymer layer in a solution including a conductive monomer and a seed material for a predetermined time period;

removing said dielectric polymer layer from said solution including said conductive monomer and said seed material and thereafter rinsing and drying said dielectric polymer layer; and

thereafter electrolessly plating an electrically conductive layer on said dielectric polymer layer.

20 (new). The method of claim 19 wherein said dielectric polymer layer is polytetrafluoroethylene.

21 (new). The method of claim 20 wherein said conductive monomer in said solution is selected from the group of monomers consisting of pyrrole monomer, aniline monomer, thiophene monomer and combinations thereof.

22 (new). The method of claim 21 wherein said seed material is palladium-tin, said monomer comprising from about 0.001 to about 0.100 percent of said solution.

23 (new). The method of claim 22 wherein said monomer comprises about 0.05 percent of said solution.

24 (new). The method of claim 22 wherein said solution further includes an oxidant.

25 (new). The method of claim 24 wherein said oxidant is selected from the group consisting of sodium persulfate, ferric chloride, cupric chloride, permanganate salt and compositions thereof.

26 (new). The method of claim 22 wherein said electrically conductive layer formed by said electroless plating includes a circuit line having a thickness of only about 0.001 inch.

27 (new). The method of claim 26 wherein said electrically conductive layer is copper.

28 (new). The method of claim 22 wherein said solution including said conductive monomer and said seed material is at a temperature of from about 20 degrees Celsius to about 30 degrees Celsius during said immersing of said dielectric polymer layer therein.

29 (new). The method of claim 19 further comprising making at least one additional circuitized substrate using the steps of claim 19 and thereafter bonding said at least one additional circuitized substrate to said circuitized substrate.

30 (new). The invention of claim 19 wherein said method is performed without a sputtering operation.